SN74LS175

Quad D Flip-Flop

The LSTTL/MSI SN74LS175 is a high speed Quad D Flip-Flop. The device is useful for general flip-flop requirements where clock and clear inputs are common. The information on the D inputs is stored during the LOW to HIGH clock transition. Both true and complemented outputs of each flip-flop are provided. A Master Reset input resets all flip-flops, independent of the Clock or D inputs, when LOW.

The LS175 is fabricated with the Schottky barrier diode process for high speed and is completely compatible with all ON Semiconductor TTL families.

- Edge-Triggered D-Type Inputs
- Buffered-Positive Edge-Triggered Clock
- Clock to Output Delays of 30 ns
- Asynchronous Common Reset
- True and Complement Output
- Input Clamp Diodes Limit High Speed Termination Effects
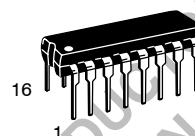
GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.75	5.0	5.25	V
T_A	Operating Ambient Temperature Range	0	25	70	°C
I_{OH}	Output Current – High			−0.4	mA
I_{OL}	Output Current – Low			8.0	mA

ON Semiconductor™

http://onsemi.com

LOW POWER SCHOTTKY

16
1

**PLASTIC
N SUFFIX
CASE 648**

16
1
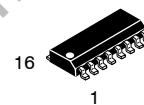
**SOIC
D SUFFIX
CASE 751B**

16
1
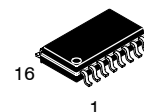
**SOEIAJ
M SUFFIX
CASE 966**

ORDERING INFORMATION

Device	Package	Shipping
SN74LS175N	16 Pin DIP	2000 Units/Box
SN74LS175D	SOIC−16	38 Units/Rail
SN74LS175DR2	SOIC−16	2500/Tape & Reel
SN74LS175M	SOEIAJ−16	See Note 1
SN74LS175MEL	SOEIAJ−16	See Note 1

1. For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

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CONNECTION DIAGRAM DIP (TOP VIEW)

16	15	14	13	12	11	10	9
V_{CC}	Q_3	$\overline{Q}_3$	D_3	D_2	$\overline{Q}_2$	Q_2	CP

1	2	3	4	5	6	7	8
$\overline{MR}$	Q_0	$\overline{Q}_0$	D_0	D_1	$\overline{Q}_1$	Q_1	GND
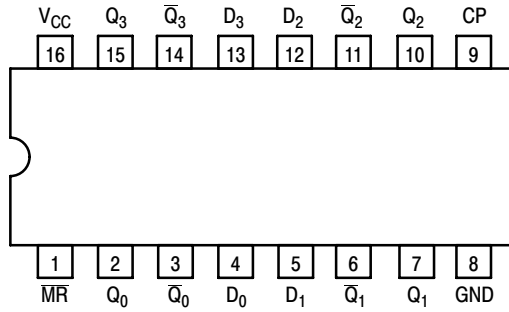
NOTE:
The Flatpak version has the same pinouts (Connection Diagram) as the Dual In-Line Package.

PIN NAMES

		LOADING (Note a)	
		HIGH	LOW
$D_0 - D_3$	Data Inputs	0.5 U.L.	0.25 U.L.
CP	Clock (Active HIGH Going Edge) Input	0.5 U.L.	0.25 U.L.
$\overline{MR}$	Master Reset (Active LOW) Input	0.5 U.L.	0.25 U.L.
$Q_0 - Q_3$	True Outputs	10 U.L.	5 U.L.
$\overline{Q}_0 - \overline{Q}_3$	Complemented Outputs	10 U.L.	5 U.L.

NOTES:
   a) 1 TTL Unit Load (U.L.) = 40 μA HIGH/1.6 mA LOW.

LOGIC SYMBOL
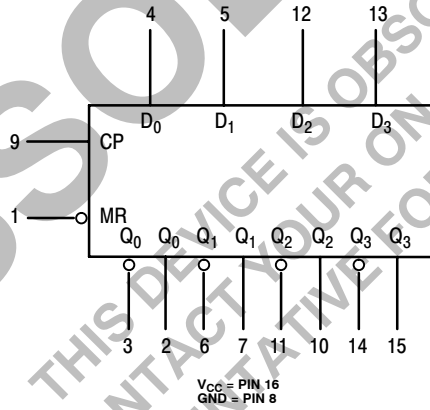
V_{CC} = PIN 16
GND = PIN 8

LOGIC DIAGRAM
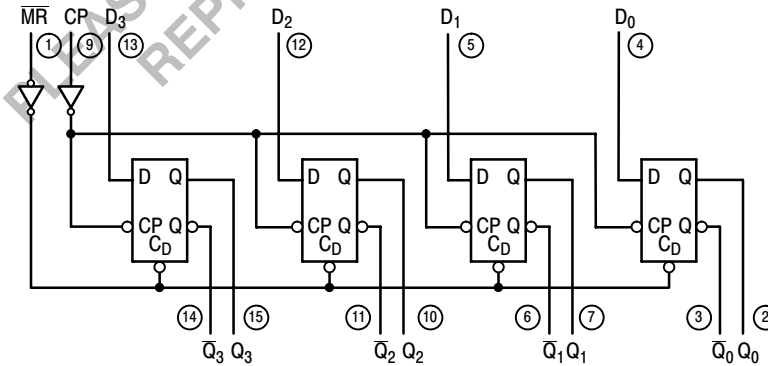
V_{CC} = PIN 16
GND = PIN 8

◯ = PIN NUMBERS

SN74LS175

FUNCTIONAL DESCRIPTION

The LS175 consists of four edge-triggered D flip-flops with individual D inputs and Q and $\overline{Q}$ outputs. The Clock and Master Reset are common. The four flip-flops will store the state of their individual D inputs on the LOW to HIGH Clock (CP) transition, causing individual Q and $\overline{Q}$ outputs to follow. A LOW input on the Master Reset ($\overline{MR}$) will force all Q outputs LOW and $\overline{Q}$ outputs HIGH independent of Clock or Data inputs.

The LS175 is useful for general logic applications where a common Master Reset and Clock are acceptable.

TRUTH TABLE

Inputs (t = n, $\overline{MR}$ = H)	Outputs (t = n+1) Note 1	
D	Q	$\overline{Q}$
L	L	H
H	H	L

Note 1: t = n + 1 indicates conditions after next clock.

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions	
V_{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V_{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V_{IK}	Input Clamp Diode Voltage		−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA	
V_{OH}	Output HIGH Voltage	2.7	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
V_{OL}	Output LOW Voltage		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
			0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input HIGH Current			20	μA	V_{CC} = MAX, V_{IN} = 2.7 V	
				0.1	mA	V_{CC} = MAX, V_{IN} = 7.0 V	
I_{IL}	Input LOW Current			−0.4	mA	V_{CC} = MAX, V_{IN} = 0.4 V	
I_{OS}	Short Circuit Current (Note 2)	−20		−100	mA	V_{CC} = MAX	
I_{CC}	Power Supply Current			18	mA	V_{CC} = MAX	

2. Not more than one output should be shorted at a time, nor for more than 1 second.

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AC CHARACTERISTICS ($T_A = 25°C$)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
f_{MAX}	Maximum Input Clock Frequency	30	40		MHz	
t_{PLH} t_{PHL}	Propagation Delay, $\overline{MR}$ to Output		20 20	30 30	ns	$V_{CC} = 5.0$ V $C_L = 15$ pF
t_{PLH} t_{PHL}	Propagation Delay, Clock to Output		13 16	25 25	ns	

AC SETUP REQUIREMENTS ($T_A = 25°C$)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
t_W	Clock or $\overline{MR}$ Pulse Width	20			ns	
t_s	Data Setup Time	20			ns	$V_{CC} = 5.0$ V
t_h	Data Hold Time	5.0			ns	
t_{rec}	Recovery Time	25			ns	

AC WAVEFORMS
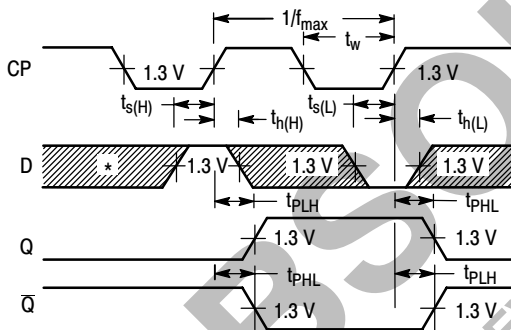
*The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 1. Clock to Output Delays, Clock Pulse Width, Frequency, Setup and Hold Times Data to Clock
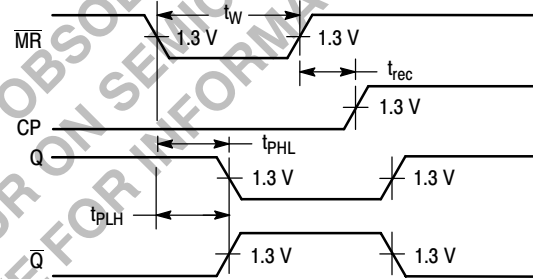
Figure 2. Master Reset to Output Delay, Master Reset Pulse Width, and Master Reset Recovery Time

DEFINITIONS OF TERMS

SETUP TIME (t_s) — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW to HIGH in order to be recognized and transferred to the outputs.

HOLD TIME (t_h) — is defined as the minimum time following the clock transition from LOW to HIGH that the logic level must be maintained at the input in order to ensure continued recognition. A negative HOLD TIME indicates that the correct logic level may be released prior to the clock transition from LOW to HIGH and still be recognized.

RECOVERY TIME (t_{rec}) — is defined as the minimum time required between the end of the reset pulse and the clock transition from LOW to HIGH in order to recognize and transfer HIGH Data to the Q outputs.

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PACKAGE DIMENSIONS

N SUFFIX
PLASTIC PACKAGE
CASE 648−08
ISSUE R
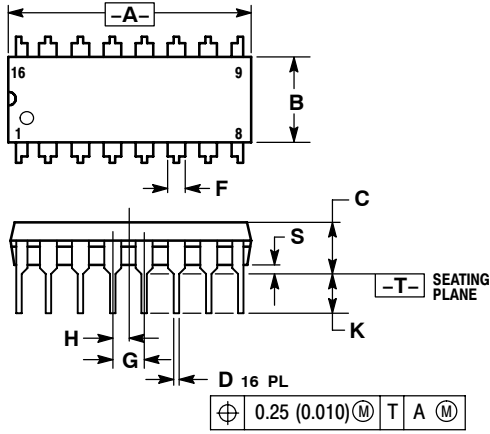
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

⊕ | 0.25 (0.010) Ⓜ | T | A Ⓜ

SN74LS175

PACKAGE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J
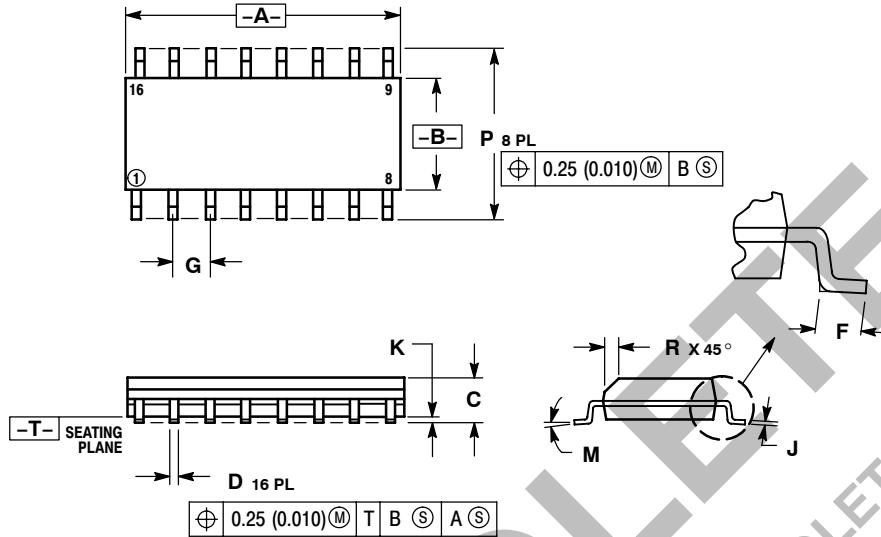
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SN74LS175

PACKAGE DIMENSIONS

M SUFFIX
SOEIAJ PACKAGE
CASE 966–01
ISSUE O
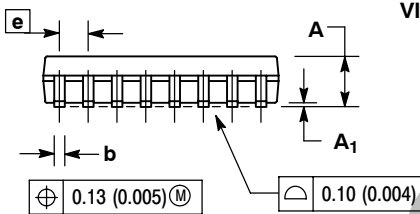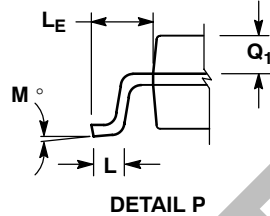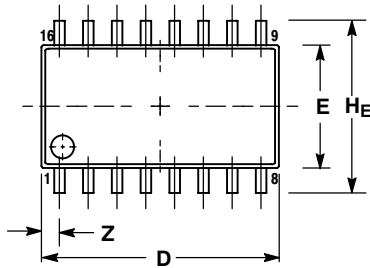
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A$_1$	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H$_E$	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L$_E$	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q$_1$	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

⊕ 0.13 (0.005) Ⓜ

△ 0.10 (0.004)

DETAIL P

VIEW P

PUBLICATION ORDERING INFORMATION

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